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# NCE N-Channel Enhancement Mode Power MOSFET

## **Description**

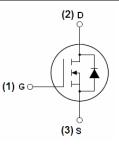
The NCE02H10T uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

- $V_{DS}$  =200V, $I_{D}$  =100A  $R_{DS(ON)}$  <18m $\Omega$  @  $V_{GS}$ =10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

## **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Schematic diagram



TO-247 top view

100% UIS TESTED! 100% ΔVds TESTED!

#### **Package Marking and Ordering Information**

| Device Marking | Device    | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| NCE02H10T      | NCE02H10T | TO-247         | -         | -          | -        |

## Absolute Maximum Ratings (T<sub>c</sub>=25°Cunless otherwise noted)

| Parameter  | Symbol                | Limit      | Unit |
|--|-----------------------|------------|------|
| Drain-Source Voltage                             | V <sub>DS</sub>       | 200        | V    |
| Gate-Source Voltage                              | V <sub>GS</sub>       | ±20        | V    |
| Drain Current-Continuous                         | I <sub>D</sub>        | 100        | Α    |
| Drain Current-Continuous(T <sub>C</sub> =100 °C) | I <sub>D</sub> (100℃) | 70.7       | Α    |
| Pulsed Drain Current                             | I <sub>DM</sub>       | 400        | Α    |
| Maximum Power Dissipation                        | P <sub>D</sub>        | 400        | W    |
| Derating factor                                  |                       | 2.67       | W/℃  |
| Single pulse avalanche energy (Note 5)           | E <sub>AS</sub>       | 1369       | mJ   |
| Operating Junction and Storage Temperature Range | $T_{J}$ , $T_{STG}$   | -55 To 175 | °C   |

#### **Thermal Characteristic**

| Thermal Resistance, Junction-to-Case (Note 2) | $R_{	heta JC}$ | 0.38 | °C/W |
|---|----------------|------|------|

# NCE02H10T

Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

| Parameter                          | Symbol              | Condition  | Min | Тур   | Max  | Unit |
|------------------------------------|---------------------|--|-----|-------|------|------|
| Off Characteristics                | •                   |  | •   |       |      |      |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA                            | 200 | 220   | -    | V    |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =200V,V <sub>GS</sub> =0V                            | -   | -     | 1    | μA   |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                            | -   | -     | ±100 | nA   |
| On Characteristics (Note 3)        |                     |  |     |       |      |      |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | $V_{DS}=V_{GS}$ , $I_{D}=250\mu A$                                   | 2   | 3     | 4    | V    |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =50A                            | -   | 13.5  | 18   | mΩ   |
| Forward Transconductance           | <b>g</b> FS         | V <sub>DS</sub> =5V,I <sub>D</sub> =50A                              | 50  | -     | -    | S    |
| Dynamic Characteristics (Note4)    |                     |  |     |       |      |      |
| Input Capacitance                  | C <sub>lss</sub>    | \/ F0\/\/ 0\/  | -   | 9382  | -    | PF   |
| Output Capacitance                 | Coss                | $V_{DS}$ =50V, $V_{GS}$ =0V,   | -   | 529   | -    | PF   |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    | F=1.0MHz   | -   | 206   | -    | PF   |
| Switching Characteristics (Note 4) |                     |  |     |       |      |      |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  |  | -   | 35    | -    | nS   |
| Turn-on Rise Time                  | t <sub>r</sub>      | $V_{DD}$ =100V, $R_L$ =15 $\Omega$                                   | -   | 30    | -    | nS   |
| Turn-Off Delay Time                | $t_{d(off)}$        | $V_{GS}$ =10 $V$ , $R_{G}$ =2.5 $\Omega$                             | -   | 55    | -    | nS   |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -   | 25    | -    | nS   |
| Total Gate Charge                  | Qg                  | \/ 400\/ L 50A   | -   | 150.9 |      | nC   |
| Gate-Source Charge                 | $Q_{gs}$            | V <sub>DS</sub> =100V,I <sub>D</sub> =50A,                           | -   | 36.8  |      | nC   |
| Gate-Drain Charge                  | $Q_{gd}$            | V <sub>GS</sub> =10V   | -   | 52.5  |      | nC   |
| Drain-Source Diode Characteristics | •                   |  | •   |       |      |      |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =50A                              | -   |       | 1.2  | V    |
| Diode Forward Current (Note 2)     | Is                  |  | -   | -     | 100  | Α    |
| Reverse Recovery Time              | t <sub>rr</sub>     | TJ = 25°C, IF = 50A  | -   | 52    |      | nS   |
| Reverse Recovery Charge            | Qrr                 | $di/dt = 100A/\mu s^{(Note3)} -$                                     |     | 80    |      | nC   |
| Forward Turn-On Time               | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |     |       |      |      |

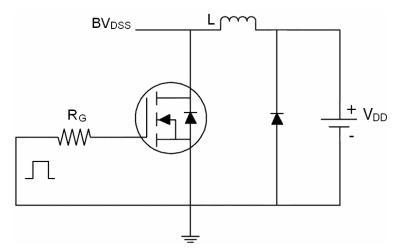
# Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5.  $E_{AS}$  condition:  $V_{DD}$ =50V, $V_{G}$ =10V,L=0.5mH,Rg=25 $\Omega$

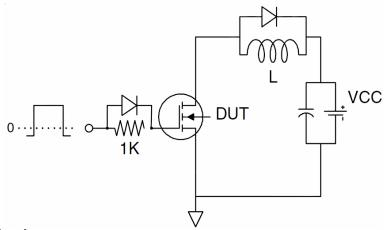


# **Test Circuit**

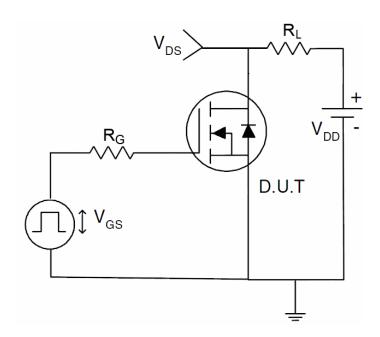
# 1) E<sub>AS</sub> test Circuits



# 2) Gate charge test Circuit



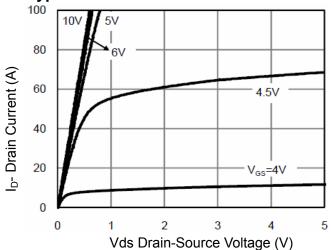
# 3) Switch Time Test Circuit



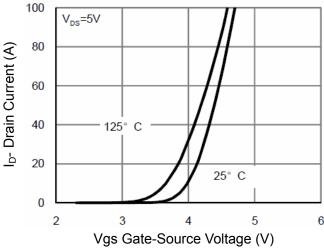
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# Typical Electrical and Thermal Characteristics (Curves)



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

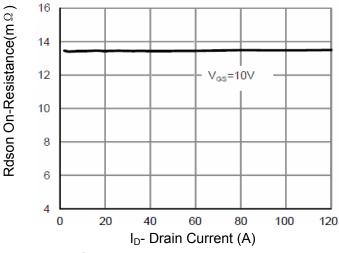
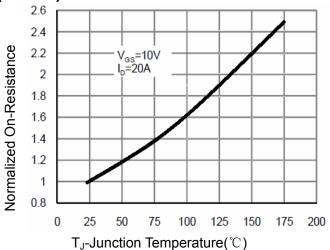


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

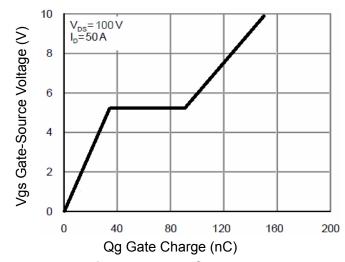


Figure 5 Gate Charge

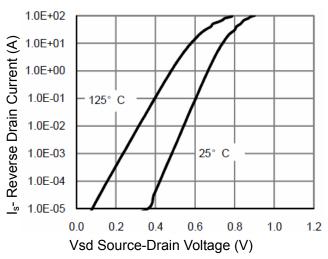


Figure 6 Source- Drain Diode Forward



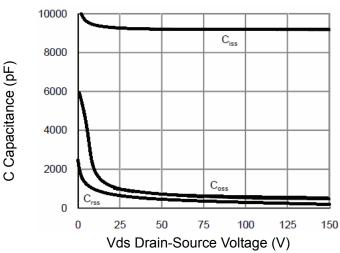


Figure 7 Capacitance vs Vds

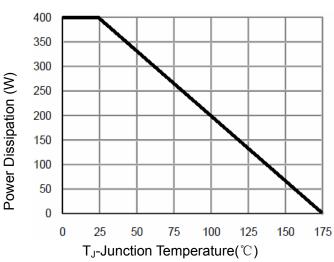


Figure 9 Power De-rating

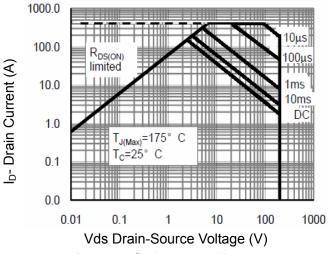


Figure 8 Safe Operation Area

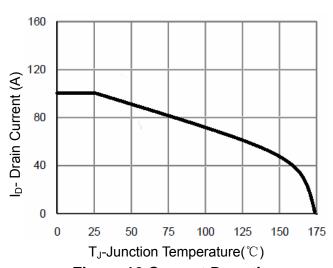


Figure 10 Current De-rating

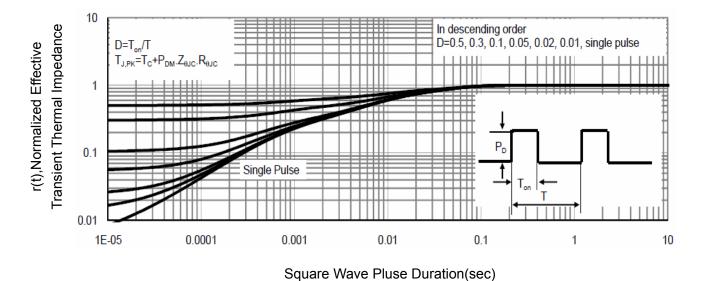
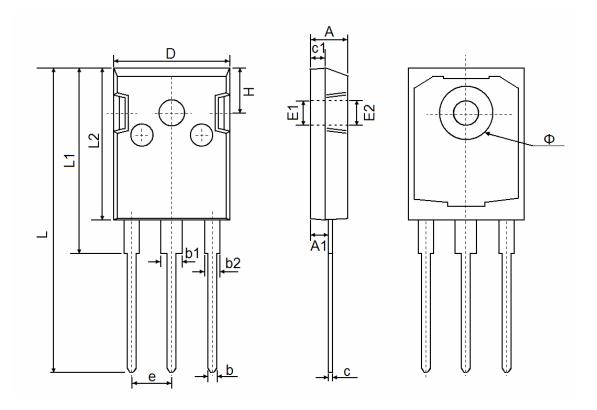


Figure 11 Normalized Maximum Transient Thermal Impedance

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# **TO-247 Package Information**



| Cumbal | Dimensions I | n Millimeters | Dimensions In Inches |           |  |  |
|--------|--------------|---------------|----------------------|-----------|--|--|
| Symbol | Min.         | Max.          | Min.                 | Max.      |  |  |
| Α      | 4.850        | 5.150         | 0.191                | 0.200     |  |  |
| A1     | 2.200        | 2.600         | 0.087                | 0.102     |  |  |
| b      | 1.000        | 1.400         | 0.039                | 0.055     |  |  |
| b1     | 2.800        | 3.200         | 0.110                | 0.126     |  |  |
| b2     | 1.800        | 2.200         | 0.071                | 0.087     |  |  |
| С      | 0.500        | 0.700         | 0.020                | 0.028     |  |  |
| c1     | 1.900        | 2.100         | 0.075                | 0.083     |  |  |
| D      | 15.450       | 15.750        | 0.608                | 0.620     |  |  |
| E1     | 3.500        | REF           | 0.138 REF            |           |  |  |
| E2     | 3.600        | 3.600 REF     |                      | 0.142 REF |  |  |
| L      | 40.900       | 41.300        | 1.610                | 1.626     |  |  |
| L1     | 24.800       | 25.100        | 0.976                | 0.988     |  |  |
| L2     | 20.300       | 20.600        | 0.799                | 0.811     |  |  |
| Ф      | 7.100        | 7.300         | 0.280                | 0.287     |  |  |
| е      | 5.450        | ) TYP         | 0.215 TYP            |           |  |  |
| Н      | 5.980        | REF           | 0.235 REF            |           |  |  |



#### http://www.ncepower.com

# NCE02H10T

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